

IN THE SPECIFICATION:

Page 1, before "BACKGROUND OF THE INVENTION, insert the following:

This is a divisional application of Application No. 09/961,430, filed on September 25, 2001.

Please substitute Paragraph [0002] for the following starting on page 1, line 16 and ending at line 23.

[0002] Conventional known electron emitting devices are roughly divided into two types including a thermoelectron emitting device and a cold-cathode electron emitting device. The cold-cathode electron emitting device includes a field emission type (referred to as a "FE type" hereinafter), a metal/insulating layer/metal type (referred to as a "MIM type" hereinafter), [[a]] and surface conduction type electron emitting devices.

Please substitute paragraph [0027] for the following starting on page 10, line 25 and ending at page 11, line 4.

[0027] In the third and fourth embodiments of the present invention, surface cleaning ~~is preferably processing~~ for cleaning the surface of the panel member is preferably performed by irradiating the surface with an electron beam, ions, an ultraviolet ray, or plasma.

Please substitute paragraph [0041] for the following starting on page 17, line 8 and ending at line 11.

[0041] In the eighth and ninth embodiments of the present invention, surface cleaning ~~is processing~~ for cleaning the surface of the panel member is performed by irradiating the surface with an electron beam, ions, an ultraviolet ray, or plasma.

Please substitute paragraph [0050] for the following starting on page 19, line 22 and ending at page 20, line 4.

[0050] Alternatively, the rear plate preferably comprises the outer frame fixed thereto with the second sealing material to form the sides of the panel fixed, the second sealing material preferably has a higher melting point than the first sealing material, or the first sealing material preferably comprises a low-melting-point ~~print~~ metal or an alloy thereof.

Please substitute paragraph [0123] for the following starting on page 46, line 7 and ending at page 47, line 2.

[0123] Then, the elevating machine 142 is moved downward, and both the RP and FP substrates are heated with the outer frame 103 fixed to the RP 101 being brought into contact with the FP 102 and pressed thereon. In heating both substrates, the panel member temperature in the sealing chamber 110 is not higher than the set temperature of the panel member in the previous processing chamber, i.e., the panel gettering chamber 109, as shown in the temperature profile of Fig. 1B. The substrates are maintained at the peak temperature at which the sealing material is softened or melted, and then the substrate temperature is decreased to bond and fix the sealing material 143. As a result, the outer frame 103 and the FP 102 are bonded together with the sealing material 143 formed on the outer frame 143, and then the sealing material 143 is fixed by curing. In this processing step, the pressure in the sealing chamber is kept at the order of 10^{-6} Pa, and thus the degree of vacuum in the panel sealed in this step is the order of 10^{-6} Pa. In this embodiment, the temperatures of the hot plates 132 and 133 are set so that the temperature of the panel member in sealing ~~are~~ is 100°C.

Please substitute paragraph [0130] for the following starting on page 49, line 6 and ending at line 11.

[0130] As the hot plates 121, 123, 127 and 132, and 136, a machine which can ~~fixing~~ fix the RP 101 with sufficient force without dropping the RP 101, for example, a chuck system using claws for mechanically catching the periphery of a substrate, an electrostatic chuck system, or a vacuum chuck system can be used.

Please substitute paragraph [0146] for the following starting on page 53, line 9 and ending at line 18.

[0146] An apparatus of a first example comprises three lines of the processing chambers starting from the front chamber 105 and ending at the panel gettering chamber 109, which are provided for the ~~tree~~ three component members including the RP 101, the FP 102 and the spacer 104 fixed to the outer frame 103 so that the ~~tree~~ three component members are separately introduced into the respective devices, and a single sealing chamber to which the three panel component members are sealed and cooled in the single sealing chamber.